

ABSTRACT

[Abstract]

Conventionally, a low-molecular-weight component tends to volatilize when added in order to improve workability, making it difficult to minimize outgassing of the component. However, the present invention is capable of minimizing outgassing during curing even when a low-molecular-weight component is added in order to improve workability and can cure at a low temperature. An epoxy resin composition of the present invention contains components (A) to (D): component (A): an epoxy resin; component (B): a compound having two or more thiol groups in one molecule; component (C): a curing accelerator; and component (D): a filler, wherein a content of an epoxy resin containing no aromatic ring in one molecule is 9.5% by mass or less with respect to a total mass of the component (A) and the epoxy resin composition comprises 25% by mass or less of the component (D) with respect to the overall composition.

No Figure